

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	1016	257/786.ccls.	USPAT; US-PGPUB
2	BRS	L4	988	257/784.ccls.	USPAT; US-PGPUB
3	BRS	L7	1356	257/773.ccls.	USPAT; US-PGPUB
4	BRS	L10	1548	Chip adj scale adj package	USPAT; US-PGPUB
5	BRS	L13	1253	Chip adj size\$2 adj package	USPAT; US-PGPUB
6	BRS	L16	355	257/786.ccls.	EPO; JPO; IBM_TDB
7	BRS	L20	451	257/784.ccls.	EPO; JPO; IBM_TDB
8	BRS	L24	444	257/773.ccls.	EPO; JPO; IBM_TDB
9	BRS	L34	424	257/775.ccls.	USPAT; US-PGPUB
10	BRS	L28	28	L1 and (wiring adj layer) and stress and (slit or aperture or hole)	USPAT; US-PGPUB
11	BRS	L31	28	L4 and (wiring adj layer) and stress and (slit or aperture or hole)	USPAT; US-PGPUB
12	BRS	L37	17	L34 and (wiring adj layer) and stress and (slit or aperture or hole)	USPAT; US-PGPUB
13	BRS	L40	1	"6181016".PN.	USPAT
14	BRS	L41	1	"6130459".PN.	USPAT

	Type	L #	Hits	Search Text	DBs
15	BRS	L4 2	1	"5981302".PN.	USPAT
16	BRS	L4 3	1	"5962919".PN.	USPAT
17	BRS	L4 4	1	"5891745".PN.	USPAT
18	BRS	L4 5	1	"5844317".PN.	USPAT
19	BRS	L4 6	179 3	(wiring adj layer) and stress and (slit or aperture or hole)	USPAT; US-PGPUB
20	BRS	L4 9	124 2	L46 and (terminal or pad or electrode) and insulating	USPAT; US-PGPUB
21	BRS	L5 2	140	L49 and dummy	USPAT; US-PGPUB
22	BRS	L5 5	67	L52 and (bump or ball or post)	USPAT; US-PGPUB